

ABSTRACT

The present invention provides a stirring mechanism for an electroplating apparatus, an electroplating apparatus, and an electroplating method. The stirring mechanism comprises a shielding region (201) and a stirring region (202), the shielding region (201) is used to weaken the flow field in the region; and the stirring region (202) comprises a plurality of first paddles (203) disposed in parallel. Wherein, during the wafer electroplating process, when the wafer notch (301) is located in the shielding region (201), the rotational speed of the wafer is a first rotational speed, when the wafer notch (301) is located in the stirring region (202), the rotational speed of the wafer is a second rotational speed, and the first rotational speed is less than the second rotational speed. The shielding region (201) is used to reduce the total amount of metal ions received by the wafer notch (301) in the shielding region (201). By setting the shielding region (201) on the stirring mechanism, and controlling the rotational speed of the wafer to be timely reduced, the total amount of metal ions received by the wafer notch (301) in the shielding region (201) is reduced, preventing the excessively high electroplating height in the peripheral region of the wafer notch during the electroplating process.